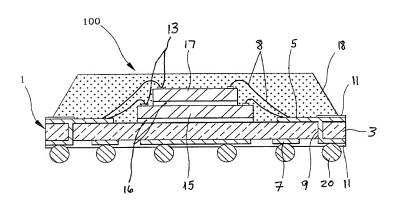
FIG. 1
-PRIOR ART-



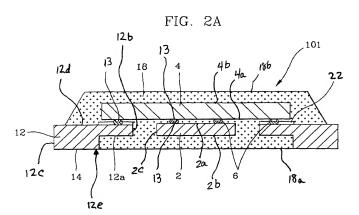


FIG. 2B

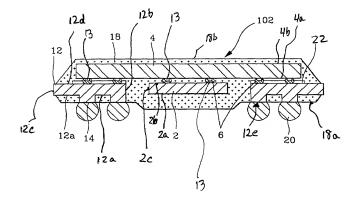


FIG. 3A

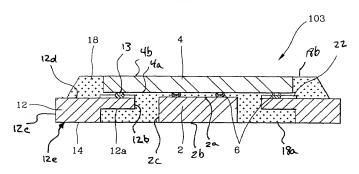
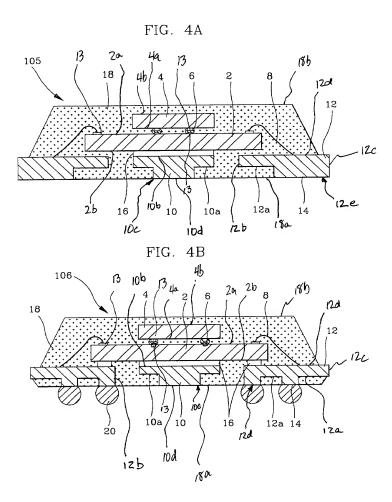


FIG. 3B

12d
13 12b
104 8b
122
12a
14 13 2a
12a
14 2 1b 6 12e
20 18a



Title of Invention: Semiconductor Package Including Stacked Chips
Docket No.: AB-1111 US Inventors: Seong Min Seo, et al.
Page 5 of 5

